Z21: Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the POF schematic.
Z22: These assemblies are ESD sensitive, ESD precautions shall be observed.
Z23: These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
Z24: These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

<table>
<thead>
<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: TIDA-01506</th>
<th>REV: E1</th>
<th>SUN REV: Not In VersionControl</th>
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</thead>
<tbody>
<tr>
<td></td>
<td>TID #: TIDA-01506</td>
<td></td>
<td></td>
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<tr>
<td>PLOT NAME = Bottom Assembly Drawing</td>
<td>GENERATED : 12/11/2017 1:37:27 PM</td>
<td></td>
<td>TEXAS INSTRUMENTS</td>
</tr>
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